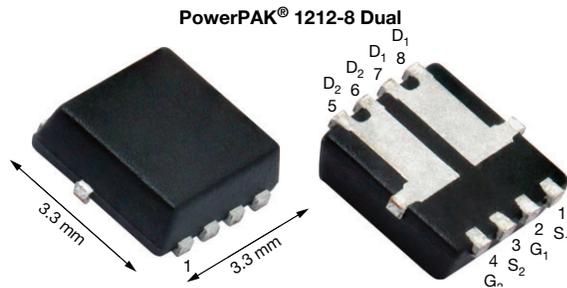


## Dual P-Channel 20 V (D-S) MOSFET



PRODUCT SUMMARY	
$V_{DS}$ (V)	-20
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = -4.5$ V	0.0201
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = -2.5$ V	0.0261
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = -1.8$ V	0.0400
$Q_g$ typ. (nC)	15.9
$I_D$ (A) <sup>f, g</sup>	6
Configuration	Dual

### FEATURES

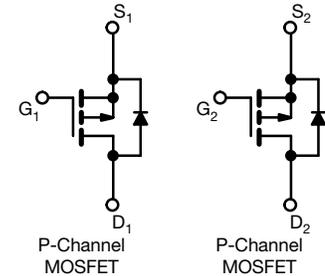
- TrenchFET<sup>®</sup> Gen III p-channel power MOSFET
- 62 % smaller package footprint than SO-8
- Thermally enhanced PowerPAK<sup>®</sup> package
- 100 %  $R_g$  and UIS tested
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### APPLICATIONS

- Load switch
- Battery protection
- Adapter and charger switch
- Hand-held and mobile devices



ORDERING INFORMATION	
Package	PowerPAK 1212-8
Lead (Pb)-free and halogen-free	SiS903DN-T1-GE3

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25$ °C, unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	$V_{DS}$	-20	V
Gate-source voltage	$V_{GS}$	$\pm 8$	
Continuous drain current ( $T_J = 150$ °C)	$I_D$	$T_C = 25$ °C	-6 <sup>g</sup>
		$T_C = 70$ °C	-6 <sup>g</sup>
		$T_A = 25$ °C	-6 <sup>a, b, g</sup>
		$T_A = 70$ °C	-6 <sup>a, b, g</sup>
Pulsed drain current ( $t = 100$ $\mu$ s)	$I_{DM}$	-40	A
Continuous source-drain diode current	$I_S$	$T_C = 25$ °C	
		$T_A = 25$ °C	2.2 <sup>a, b</sup>
Single pulse avalanche current	$I_{AS}$	14	mJ
Single pulse avalanche energy	$E_{AS}$	9.8	
Maximum power dissipation	$P_D$	$T_C = 25$ °C	23
		$T_C = 70$ °C	14.8
		$T_A = 25$ °C	2.6 <sup>a, b</sup>
		$T_A = 70$ °C	1.7 <sup>a, b</sup>
Operating junction and storage temperature range	$T_J, T_{stg}$	-55 to +150	°C
Soldering recommendations (peak temperature) <sup>c, d</sup>		260	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient <sup>a, e</sup>	$t \leq 10$ s	$R_{thJA}$	38	48	°C/W
Maximum junction-to-case (drain)	Steady state	$R_{thJC}$	4.3	5.4	

### Notes

- Surface mounted on 1" x 1" FR4 board
- $t = 10$  s
- See solder profile ([www.vishay.com/doc?73257](http://www.vishay.com/doc?73257)). The PowerPAK 1212-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 94 °C/W
- Based on  $T_C = 25$  °C
- Package limited



SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0\text{ V}$ , $I_D = -250\text{ }\mu\text{A}$	-20	-	-	V
$V_{DS}$ temperature coefficient	$\Delta V_{DS}/T_J$	$I_D = -250\text{ }\mu\text{A}$	-	-13.7	-	mV/ $^\circ\text{C}$
$V_{GS(th)}$ temperature coefficient	$\Delta V_{GS(th)}/T_J$		-	-2.6	-	
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -250\text{ }\mu\text{A}$	-0.4	-	-1	V
Gate-source leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 8\text{ V}$	-	-	$\pm 100$	nA
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = -20\text{ V}$ , $V_{GS} = 0\text{ V}$	-	-	1	$\mu\text{A}$
		$V_{DS} = -20\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 55\text{ }^\circ\text{C}$	-	-	10	
On-state drain current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \leq -5\text{ V}$ , $V_{GS} = -4.5\text{ V}$	-10	-	-	A
Drain-source on-state resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = -4.5\text{ V}$ , $I_D = -5\text{ A}$	-	0.0167	0.0201	$\Omega$
		$V_{GS} = -2.5\text{ V}$ , $I_D = -4\text{ A}$	-	0.0218	0.0261	
		$V_{GS} = -1.8\text{ V}$ , $I_D = -2.5\text{ A}$	-	-	0.0400	
Forward transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = -1.8\text{ V}$ , $I_D = -9.5\text{ A}$	-	32	-	S
<b>Dynamic <sup>b</sup></b>						
Input capacitance	$C_{iss}$	$V_{DS} = -10\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1\text{ MHz}$	-	2565	-	pF
Output capacitance	$C_{oss}$		-	260	-	
Reverse transfer capacitance	$C_{rss}$		-	240	-	
Total gate charge	$Q_g$	$V_{DS} = -10\text{ V}$ , $V_{GS} = -4.5\text{ V}$ , $I_D = -9.5\text{ A}$	-	28	42	nC
		$V_{DS} = -10\text{ V}$ , $V_{GS} = -2.5\text{ V}$ , $I_D = -9.5\text{ A}$	-	15.9	24	
Gate-source charge	$Q_{gs}$	$V_{DS} = -10\text{ V}$ , $V_{GS} = -2.5\text{ V}$ , $I_D = -9.5\text{ A}$	-	3.5	-	
Gate-drain charge	$Q_{gd}$		-	5.6	-	
Gate resistance	$R_g$	$f = 1\text{ MHz}$	2.22	11.1	22.2	$\Omega$
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -10\text{ V}$ , $R_L = 1.3\text{ }\Omega$ $I_D \cong -7.6\text{ A}$ , $V_{GEN} = -4.5\text{ V}$ , $R_g = 1\text{ }\Omega$	-	30	45	ns
Rise time	$t_r$		-	54	81	
Turn-off delay time	$t_{d(off)}$		-	135	203	
Fall time	$t_f$		-	63	95	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -10\text{ V}$ , $R_L = 1.3\text{ }\Omega$ $I_D \cong -7.6\text{ A}$ , $V_{GEN} = -8\text{ V}$ , $R_g = 1\text{ }\Omega$	-	12	20	
Rise time	$t_r$		-	33	50	
Turn-off delay time	$t_{d(off)}$		-	160	240	
Fall time	$t_f$		-	60	90	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous source-drain diode current	$I_S$	$T_C = 25\text{ }^\circ\text{C}$	-	-	6 <sup>c</sup>	A
Pulse diode forward current	$I_{SM}$		-	-	40	
Body diode voltage	$V_{SD}$	$I_S = -7.6\text{ A}$ , $V_{GS} = 0\text{ V}$	-	0.8	1.2	V
Body diode reverse recovery time	$t_{rr}$	$I_F = -7.6\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $T_J = 25\text{ }^\circ\text{C}$	-	26	40	ns
Body diode reverse recovery charge	$Q_{rr}$		-	16	24	nC
Reverse recovery fall time	$t_a$		-	12	-	ns
Reverse recovery rise time	$t_b$		-	14	-	

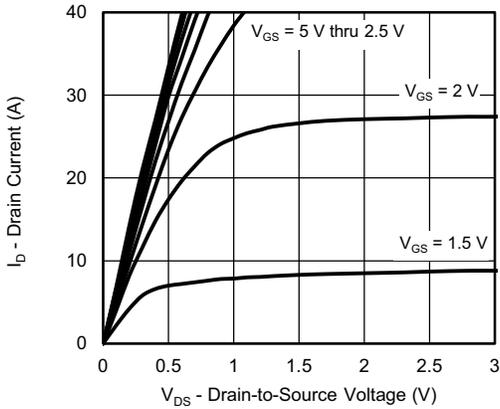
**Notes**

- Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$
- Guaranteed by design, not subject to production testing
- Package limited

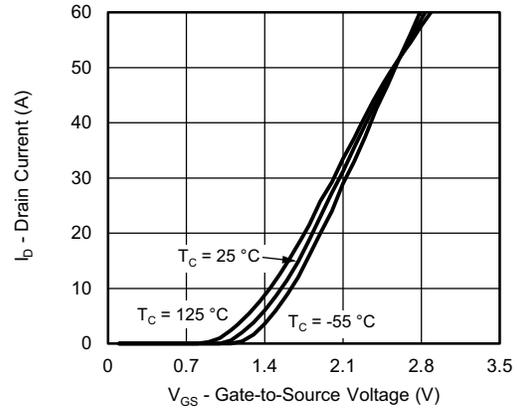
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



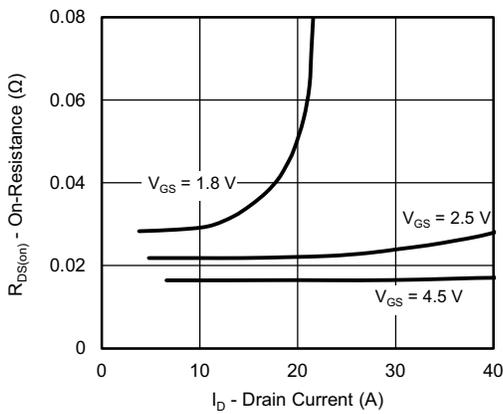
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



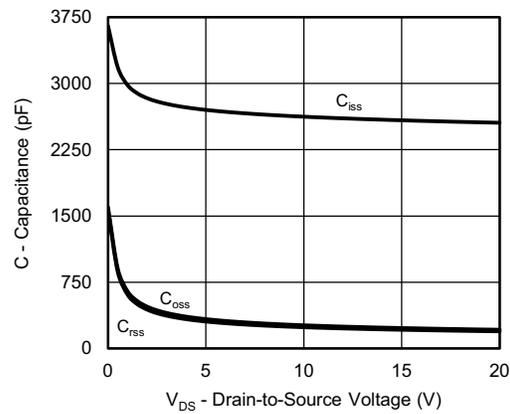
Output Characteristics



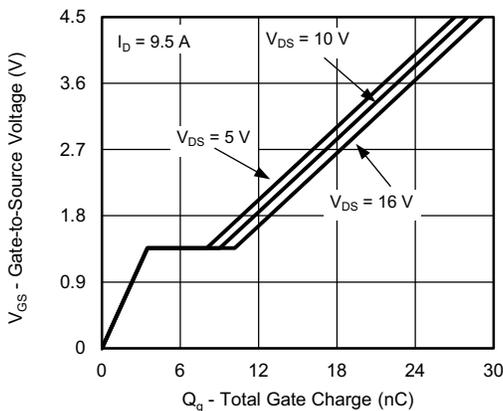
Transfer Characteristics



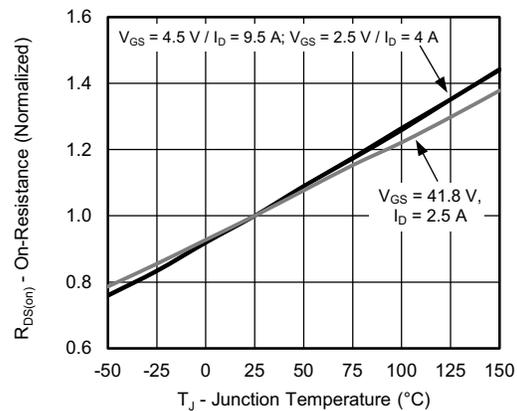
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



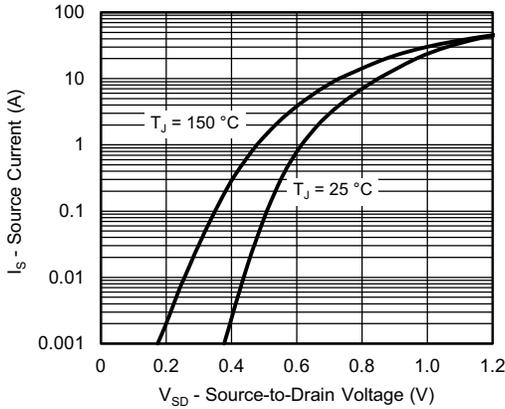
Gate Charge



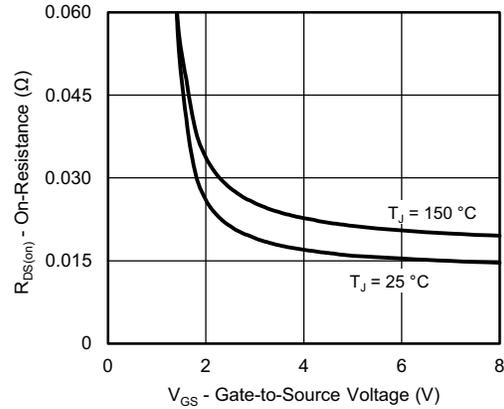
On-Resistance vs. Junction Temperature



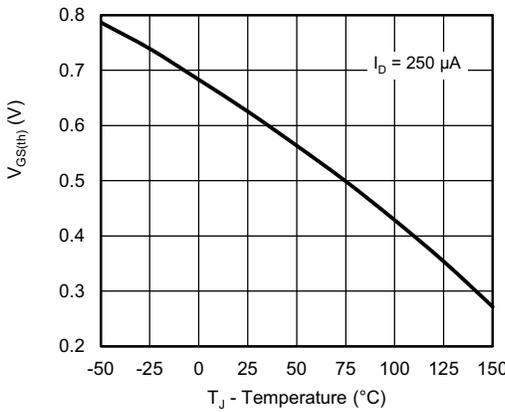
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



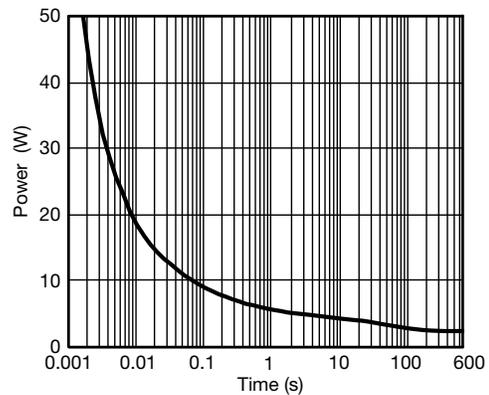
Source-Drain Diode Forward Voltage



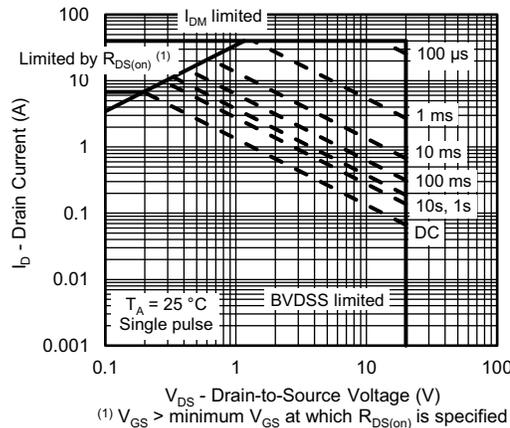
On-Resistance vs. Gate-to-Source Voltage



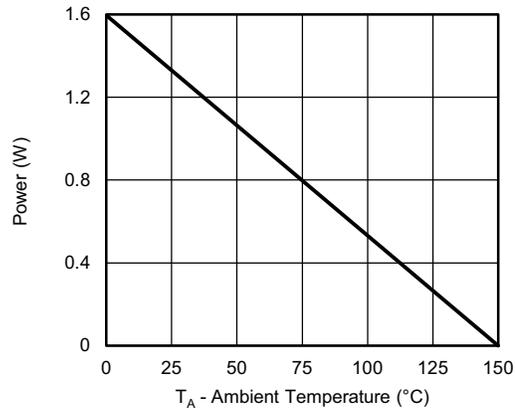
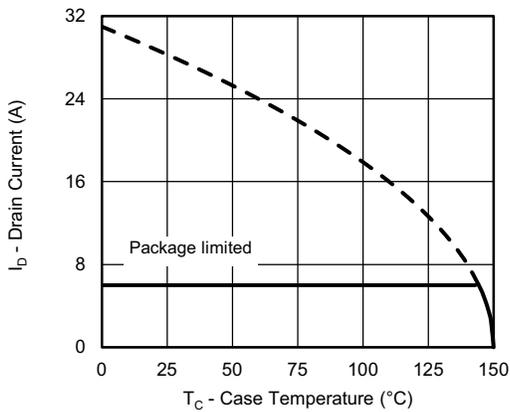
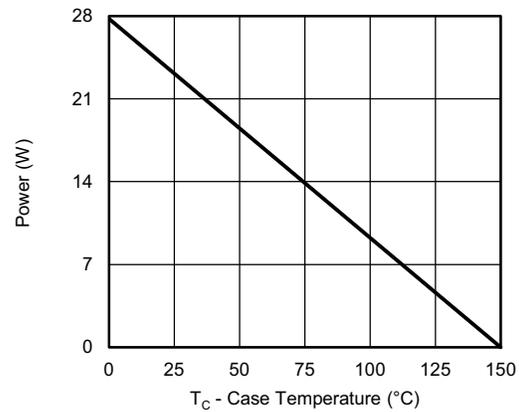
Threshold Voltage



Single Pulse Power, Junction-to-Ambient



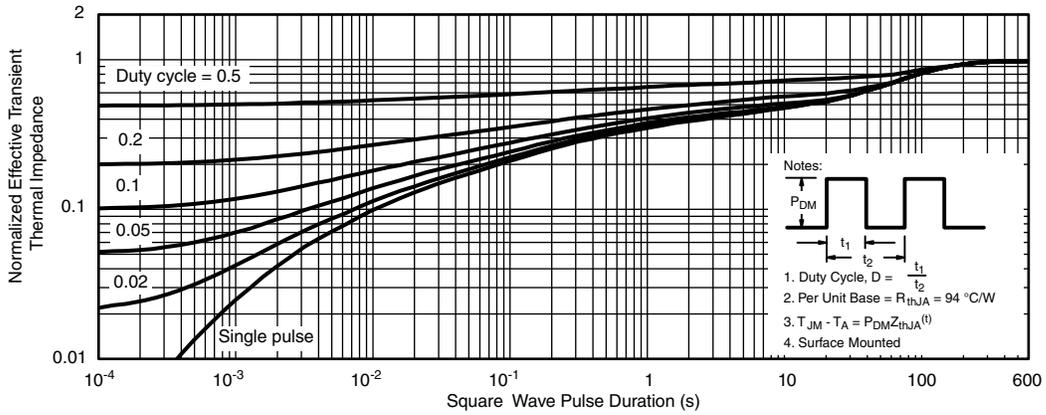
Safe Operating Area, Junction-to-Ambient

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Power Junction to Ambient**

**Current Derating <sup>a</sup>**

**Power Derating**
**Note**

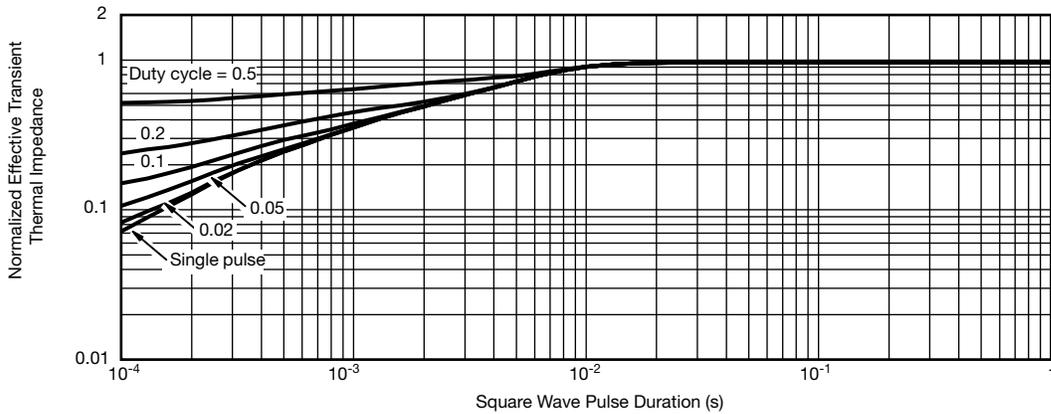
- a. The power dissipation  $P_D$  is based on  $T_J$  max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

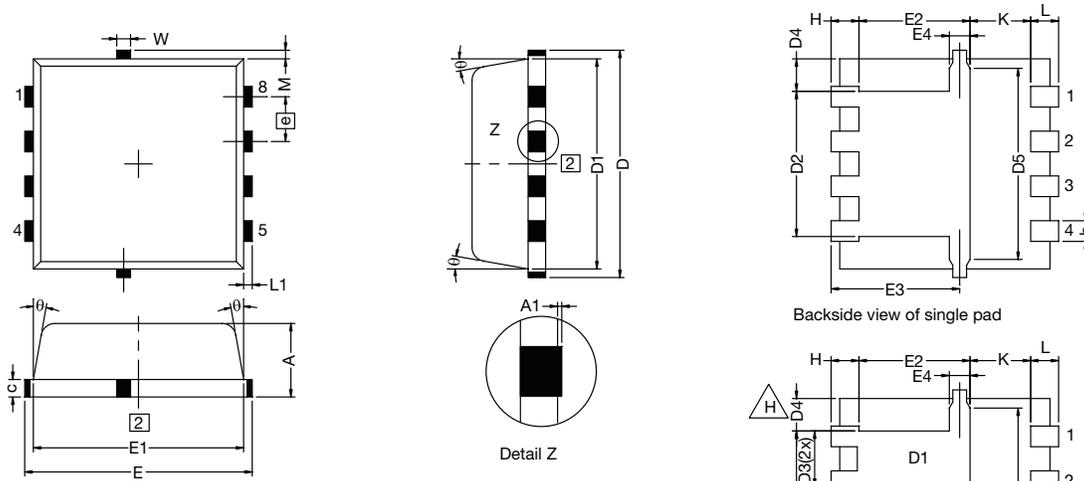


Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see [www.vishay.com/ppg?75603](http://www.vishay.com/ppg?75603).



PowerPAK® 1212-8, (Single / Dual)



- Notes**
- 1. Inch will govern
  - [2] Dimensions exclusive of mold gate burrs
  - 3. Dimensions exclusive of mold flash and cutting burrs

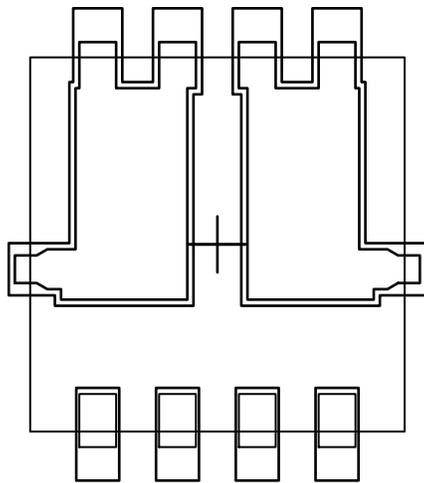
Backside view of single pad

Backside view of dual pad

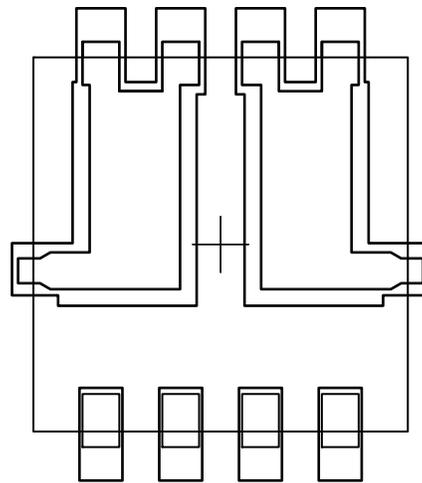
DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.97	1.04	1.12	0.038	0.041	0.044
A1	0.00	-	0.05	0.000	-	0.002
b	0.23	0.30	0.41	0.009	0.012	0.016
c	0.23	0.28	0.33	0.009	0.011	0.013
D	3.20	3.30	3.40	0.126	0.130	0.134
D1	2.95	3.05	3.15	0.116	0.120	0.124
D2	1.98	2.11	2.24	0.078	0.083	0.088
D3	0.48	-	0.89	0.019	-	0.035
D4	0.47 typ.			0.0185 typ		
D5	2.3 typ.			0.090 typ		
E	3.20	3.30	3.40	0.126	0.130	0.134
E1	2.95	3.05	3.15	0.116	0.120	0.124
E2	1.47	1.60	1.73	0.058	0.063	0.068
E3	1.75	1.85	1.98	0.069	0.073	0.078
E4	0.034 typ.			0.013 typ.		
e	0.65 BSC			0.026 BSC		
K	0.86 typ.			0.034 typ.		
K1	0.35	-	-	0.014	-	-
H	0.30	0.41	0.51	0.012	0.016	0.020
L	0.30	0.43	0.56	0.012	0.017	0.022
L1	0.06	0.13	0.20	0.002	0.005	0.008
θ	0°	-	12°	0°	-	12°
W	0.15	0.25	0.36	0.006	0.010	0.014
M	0.125 typ.			0.005 typ.		
ECN: S16-2667-Rev. M, 09-Jan-17						
DWG: 5882						



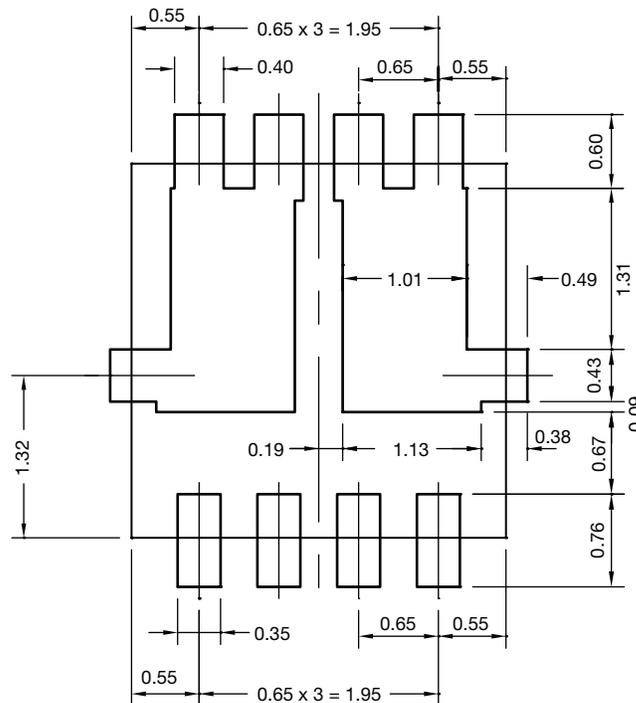
# Recommended Land Pattern for PowerPAK® 1212-8 Dual



For BW package



For BWL package





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